



PRESS RELEASE

## **FAE TECHNOLOGY ANNOUNCES INDUSTRIAL MODULES WITH NATIVE AI FOR HIGHLY-COMPLEX APPLICATIONS AT EMBEDDED WORLD 2026**

*FAE Technology joins Qualcomm Technologies' Partner Network, a global program for companies developing platforms based on Qualcomm Technologies' platforms.*

Gazzaniga (BG), March 11, 2026 — FAE Technology S.p.A. - Benefit Company ("**FAE Technology**" or the "**Company**"), Tech company and parent of the Italian advanced electronics and space technology solutions sector Group of the same name (the "**Group**"), is collaborating with **Qualcomm Technologies, Inc.**, a global leader in edge AI, high-performance, low-power computing, and advanced connectivity.

At **Embedded World 2026**, the main international embedded electronics event being held at the Nuremberg Messe, FAE Technology presents the first concrete result of this collaboration: two new industrial modules, powered by the Qualcomm Dragonwing™ IQ6 Series and Qualcomm Dragonwing™ Q6 Series. The two modules - Nari and Deva - are designed for advanced industrial applications and highly-performing connected devices, integrate edge processing capabilities and native artificial intelligence, and adopt an optimized architecture for high-performance, energy efficiency and reliability over extended life cycles. The solutions are already integrated with foundries.io, enabling the development of applications that are security-focused, updatable and can help to meet cyber resilience requirements.

The architectures are engineered for industrial automation systems, robotics, machine vision devices, edge AI and advanced IoT infrastructures, areas where powerful local computing capacity, energy efficiency and business continuity over extended life cycles are required.

The adoption of high-performance state-of-the-art technologies with native artificial intelligence strengthens FAE Technology's position as a deep tech player in high-complexity embedded segments. These new platforms offer an optimal architecture for the development of advanced connected devices, delivering powerful power-optimized performance. Specifically designed for the industrial sector, they feature extended support. In this way, FAE Technology consolidates its ability to design and integrate complex hardware-software platforms on high-performance architectures, managed throughout the entire development cycle, from design to industrial validation.



FAE Technology has also joined the Qualcomm Partner Network IoT & Industrial track, a global program dedicated to companies developing platforms based on Qualcomm Technologies. It provides access to advanced resources, dedicated development tools, and partner ecosystem for next-generation embedded architectures.

**Gianmarco Lanza**, Chairperson and Chief Executive Officer of FAE Technology, underlined: *"Collaborating with a global player like Qualcomm Technologies allows us to operate on frontier technologies and further strengthen our deep tech positioning, expanding development opportunities in international markets that demand high-performance and singular engineering capabilities. It is in these contexts that we intend to continue to grow."*

*"Presenting these modules - adds Lanza - is in step with our industrial evolution: we are consolidating our ability to design and integrate high-performance platforms geared towards highly-complex industrial settings. The value lies not only in the technology adopted, but in the speed with which we integrate it to proprietary architectures, turning it into industrializable products with extended life cycles and high levels of reliability"*.

**Dario Pennisi**, Chief Technology Officer of FAE Technology, stated: *"We have designed these platforms for applications that require high computing capacity, efficient power management and AI processing directly at the edge. The architecture was developed with an approach focused on robustness and longevity. The integration with foundries.io enables customers to accelerate the development of security-focused, upgradeable devices to help customers to meet cybersecurity requirements"*.

**Eric Mazzoleni**, Vice President, Sales, Qualcomm Germany GmbH, said: *"Qualcomm Dragonwing platforms are powering advanced industrial modules that deliver AI and high-performance computing at the edge. With the launch of these new modules, FAE Technology is well positioned to bring best-in-class capabilities into customer designs across industrial automation, robotics and beyond"*.

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**FAE Technology S.p.A. - Benefit Company** is the Tech company leading the Italian Group of the same name, listed on the Euronext Growth Milan market of the Italian Stock Exchange, and is an advanced electronics and space technology solutions leader. Through the Electronics Division, the Group operates as an Original Design Manufacturer (ODM) and comprises several highly-specialized companies: FAE Technology, Elettronica GF, IpTronix and MAS Elettronica. The Space division operates through Kayser Italia and Kayser Space, providing technology and support for space exploration and in-orbit activities. Together, the various entities form a technology platform that covers the entire life cycle of a solution: from R&D to co-design, from material supply to prototyping and production and from advanced testing to after-sales support. Founded in 1990 in Gazzaniga (BG) by Francesco Lanza, who began by producing a small series of electronic boards, FAE Technology has been led since 2008 by his son Gianmarco Lanza, current Chairperson and Chief Executive Officer. FAE Technology is known for its focus on innovation - promoting open innovation and shared research at the "Kilometro Rosso" hub - and on sustainability and corporate social responsibility, becoming a Benefit Company on May 13, 2022. FAE Technology benefits from memberships with renowned universities and research centers, including the "Senseable City Lab" at the MIT (Massachusetts Institute of Technology) in Boston, in addition to strategic partnerships with major sector players. The Group's ability to tap into both organic and acquisition-led growth opportunities, including through supply chain and market consolidation, strengthens its role as a strategic technology development partner to companies and organizations. The Group reports a consolidated value of production of Euro 75.5 million for 2024, up 18.2% on 2023.

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